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General Description

The MAX1366/MAX1368 low-power, 4.5- and 3.5-digit, panel meters feature an integrated sigma-delta analogto-digital converter (ADC), LED display drivers, voltage digital-to-analog converter (DAC), and a 4-20mA (or 0 to 16mA) current driver.

EVALUATION KIT

The MAX1366/MAX1368's analog input voltage range is programmable to either ±2V or ±200mV. The MAX1368 drives a 3.5-digit (±1999 count) display and the MAX1366 drives a 4.5-digit (±19,999 count) display. The ADC output directly drives the LED display as well as the voltage DAC, which, in turn, drives the 4-20mA (or 0 to 16mA) current-loop output.

In normal operation, the 0 to 16mA/4-20mA currentloop output follows the ±2V or ±200mV analog input to drive remote panel-meter displays, data loggers, and other industrial controllers. For added flexibility, the MAX1366/MAX1368 allow direct access to the ADC result, DAC output, and the V/I converter input.

The sigma-delta ADC does not require external precision integrating capacitors, autozero capacitors, crystal oscillators, charge pumps, or other circuitry commonly required in dual-slope ADC panel-meter circuits. Onchip analog input and reference buffers allow direct interface with high-impedance signal sources. Excellent common-mode rejection and digital filtering provides greater than 100dB rejection of simultaneous 50Hz and 60Hz line noise. Other features include data hold and peak detection and overrange/underrange detection.

The MAX1366/MAX1368 require a 2.7V to 5.25V supply, a 4.75V to 5.25V V/I supply, and a 7V to 30V loop supply. They are available in a space-saving (7mm x 7mm), 48-pin TQFP package and operate over the extended (-40°C to +85°C) temperature range.

Applications

- Industrial Process Control
- Automated Test Equipment
- **Data-Acquisition Systems**
- **Digital Panel Meters**
- **Digital Voltmeters**
- **Digital Multimeters**

Pin Configuration appears at end of data sheet.

Typical Operating Circuits appear at end of data sheet.

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Features

♦ Microcontroller (µC)-Interface, Digital Panel Meter 20-Bit Sigma-Delta ADC

4.5-Digit Resolution (±19,999 Count, MAX1366) 3.5-Digit Resolution (±1999 Count, MAX1368) No Integrating/Autozeroing Capacitors **100M** Ω Input Impedance ±200mV or ±2.000V Input Range

LED Display Common-Cathode 7-Segment LED Driver Programmable LED Current (0 to 20mA) 2.5Hz Update Rate

Output DAC and Current Driver ±15-Bit DAC with 14-Bit Linear V/I Converter Selectable 0 to 16mA or 4–20mA Current Output **Unipolar/Bipolar Modes** ±50µA Zero Scale, ±40ppmFS/°C (typ) ±0.5% Gain Error, ±25ppmFS/°C (typ) Separate 7V to 30V Supply for Current-Loop Output

- 2.7V to 5.25V ADC/DAC Supply
- ♦ 4.75V to 5.25V V/I Converter Supply
- Internal 2.048V Reference or External Reference
- ◆ SPI[™]-/QSPI[™]-/MICROWIRE[™]-Compatible Serial Interface
- ♦ 48-Pin, 7mm x 7mm TQFP Package

Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX1366ECM	-40°C to +85°C	48 TQFP
MAX1368ECM	-40°C to +85°C	48 TQFP

Selector Guide

PART	PACKAGE CODE	RESOLUTION (DIGITS)
MAX1366ECM	C48-6	4.5
MAX1368ECM	C48-6	3.5

Maxim Integrated Products 1

For pricing, delivery, and ordering information, please contact Maxim/Dallas Direct! at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

ABSOLUTE MAXIMUM RATINGS

(With reference to GND, unless of	therwise specified.)	SEG_ to LEDG	0.3V to (V _{LEDV} + 0.3V
AV _{DD} , DV _{DD}	-0.3V to +6.0V	DIG_ to LEDG	0.3V to (VLEDV + 0.3V
AIN+, AIN-, REF+, REF	V _{NEGV} to (AV _{DD} + 0.3V)	LOWBATT	0.3V to (AV _{DD} + 0.3V
REG_FORCE, CMP, DAC_VDD, D	DACVOUT,	REF_DAC	0.3V to (AV _{DD} + 0.3V
CONV_IN, 4-20OUT	0.3V to (AV _{DD} + 0.3V)	DACVOUT	0.3V to (AV _{DD} + 0.3V
EN_BPM, EN_I, REFSELE, DACD	ATA_SEL,	DIG_ Sink Current	
CLK, EOC, CS_DAC, SCLK, DI	N	DIG_ Source Current	50mA
DOUT	0.3V to (DV _{DD} + 0.3V)	SEG_ Sink Current	50mA
NEGV	2.6V to (AV _{DD} + 0.3V)	SEG_ Source Current	50mA
LED_EN	0.3V to (DV _{DD} + 0.3V)	Maximum Current Input into Any	Other Pin50mA
SET	0.3V to (AV _{DD} + 0.3V)	Continuous Power Dissipation (T	$A = +70^{\circ}C$
REG_AMP, REG_VDD	-0.3V to +6.0V	48-Pin TQFP (derate 22.7mW/	^o C above +70°C)1818.2mV
LEDG	-0.3V to +0.3V	Operating Temperature Range.	
GND_DAC	-0.3V to +0.3V	Storage Temperature Range	60°C to +150°C
GND_V/I	0.3V to +0.3V	Lead Temperature (soldering, 10	0s)+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(AV_{DD} = DV_{DD} = DAC_VDD = +2.7V \text{ to } +5.25V, \text{ GND} = 0, \text{ LEDG} = 0, \text{ V}_{\text{LEDV}} = +2.7V \text{ to } +5.25V, \text{ V}_{\text{REF}+} - \text{ V}_{\text{REF}-} = 2.048V \text{ (external reference)}, \text{ V}_{\text{EXT}} = 7V, \text{ V}_{\text{REG}_AMP} = +5.0V, \text{ C}_{\text{REF}+} = 0.1\mu\text{F}, \text{ REF}- = \text{GND}, \text{ C}_{\text{NEGV}} = 0.1\mu\text{F}. \text{ Internal clock mode, unless otherwise noted}. \text{ All specifications are at } T_{\text{A}} = T_{\text{MIN}} \text{ to } T_{\text{MAX}}. \text{ Typical values are at } T_{\text{A}} = +25^{\circ}\text{C}, \text{ unless otherwise noted}.$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	МАХ	UNITS
ADC ACCURACY						
Naine Free Decelution		MAX1366	-19,999		+19,999	Coursto
Noise-Free Resolution		MAX1368	-1999		+1999	Counts
Internet Nerlinserity (Nets 1)	INII	2.000V range		±1		Coursto
integral Nonlinearity (Note 1)	IINL	200mV range		±1		Counts
Range-Change Ratio		(V _{AIN+} - V _{AIN-} = 0.100V) on 200mV range; (V _{AIN+} - V _{AIN-} = 0.100V) on 2.0V range		10:1		Ratio
Rollover Error		$V_{AIN+} - V_{AIN-} = $ full scale		±1		Counts
Output Noise				10		μV _{P-P}
Offset Error (Zero Input Reading)		$V_{AIN+} - V_{AIN-} = 0$ (Note 2)	-0		+0	Counts
Gain Error		(Note 3)	-0.5		+0.5	%FSR
Offset Drift (Zero Reading Drift)		$V_{AIN+} - V_{AIN-} = 0$ (Note 4)		0.1		µV/°C
Gain Drift				±1		ppm/°C
INPUT CONVERSION RATE						
External Clock Frequency				4.9152		MHz
External Clock Duty Cycle			40		60	%
Lindata Pata		Internal clock		5		⊔ -7
		External clock, f _{CLK} = 4.9152MHz	5		ΠZ	
ANALOG INPUTS (AIN+, AIN-) (by	/pass to GNI	D with 0.1µF or greater capacitors)				
		RANGE bit = 0	-2.0		+2.0	V
		RANGE bit = 1	-0.2		+0.2	

ELECTRICAL CHARACTERISTICS (continued)

 $(AV_{DD} = DV_{DD} = DAC_VDD = +2.7V$ to +5.25V, GND = 0, LEDG = 0, $V_{LEDV} = +2.7V$ to +5.25V, $V_{REF+} - V_{REF-} = 2.048V$ (external reference), $V_{EXT} = 7V$, $V_{REG_AMP} = +5.0V$, $C_{REF+} = 0.1\mu$ F, REF- = GND, $C_{NEGV} = 0.1\mu$ F. Internal clock mode, unless otherwise noted. All specifications are at $T_A = T_{MIN}$ to T_{MAX} . Typical values are at $T_A = +25^{\circ}$ C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
AIN Absolute Input Voltage Range to GND			-2.2		+2.2	V
Normal-Mode 50Hz and 60Hz		Internal clock mode, 50Hz and 60Hz ±2%		100		-10
Rejection (Simultaneously)		External clock mode, 50Hz and 60Hz ±2%, f _{CLK} = 4.9152MHz		100		ав
Common-Mode 50Hz and 60Hz Rejection (Simultaneously)	CMR	For 50Hz and 60Hz ±2%, R _{SOURCE} < $10k\Omega$		150		dB
Common-Mode Rejection	CMR	At DC		100		dB
Input Leakage Current				10		nA
Input Capacitance				10		pF
Average Dynamic Input Current		(Note 6)	-20		+20	nA
LOW-BATTERY VOLTAGE MON	TOR (LOWB	ATT)				
LOWBATT Trip Threshold				2.048		V
LOWBATT Leakage Current				10		рΑ
Hysteresis				20		mV
INTERNAL REFERENCE (REF- =	GND, INTRE	F = DV _{DD})				
REF Input Voltage	V _{REF}	$AV_{DD} = 5V$	2.007	2.048	2.089	V
REF Output Short-Circuit Current				1		mA
REF Output Temperature Coefficient	TCVREF			40		ppm/°C
Load Regulation		$I_{\text{SOURCE}} = 0$ to 300µA, $I_{\text{SINK}} = 0$ to 30µA		6		μV/μA
Line Regulation				50		μV/V
		0.1Hz to 10Hz		25		
Noise voitage		10Hz to 10kHz		400		μνρ-ρ
EXTERNAL REFERENCE (INTRE	F BIT = 0)					
REF Input Voltage		Differential, (VREF+ - VREF-)		2.048		V
Absolute REF+, REF- Input Voltage to GND (V _{REF+} must be greater than V _{REF-})			-2.2		+2.2	V
Normal-Mode 50Hz and 60Hz		Internal clock mode, 50Hz and 60Hz ±2%		100		dP
Rejection (Simultaneously)		External clock mode, 50Hz and 60Hz \pm 2%, f _{CLK} = 4.9152MHz		120		uБ
Common-Mode 50Hz and 60Hz Rejection (Simultaneously)	CMR	For 50Hz and 60Hz \pm 2%, R _{SOURCE} < 10k Ω		150		dB
Common-Mode Rejection	CMR	At DC		100		dB
Input Leakage Current				10		nA



ELECTRICAL CHARACTERISTICS (continued)

 $(AV_{DD} = DV_{DD} = DAC_VDD = +2.7V$ to +5.25V, GND = 0, LEDG = 0, $V_{LEDV} = +2.7V$ to +5.25V, $V_{REF+} - V_{REF-} = 2.048V$ (external reference), $V_{EXT} = 7V$, $V_{REG_AMP} = +5.0V$, $C_{REF+} = 0.1\mu$ F, REF- = GND, $C_{NEGV} = 0.1\mu$ F. Internal clock mode, unless otherwise noted. All specifications are at $T_A = T_{MIN}$ to T_{MAX} . Typical values are at $T_A = +25^{\circ}$ C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
Input Capacitance				10		рF
Average Dynamic Input Current		(Note 6)	-20		+20	nA
CHARGE PUMP			•			
Output Voltage	NEGV	$C_{NEGV} = 0.1 \mu F$ to GND	-2.60	-2.42	-2.30	V
DIGITAL INPUTS (SCLK, DIN, \overline{CS}	, CLK)					
Input Current	I _{IN}	$V_{IN} = 0 \text{ or } DV_{DD}$	-10		+10	μA
Input Low Voltage	VINL				0.3 x DV _{DD}	V
Input High Voltage	VINH		0.7 x DV _{DD}			V
Input Hysteresis	V _{HYS}	$DV_{DD} = 3V$		200		mV
DIGITAL OUTPUTS (DOUT, EOC)						
Output Low Voltage	VOL	I _{SINK} = 1mA			0.4	V
Output High Voltage	VOH	ISOURCE = 200µA	0.8 x D _{VDD}			V
Tri-State Leakage Current	١L		-10		+10	μA
Tri-State Output Capacitance	Cout			15		рF
ADC POWER SUPPLY (Note 10)						
AV _{DD} Voltage	AV _{DD}		2.70		5.25	V
DV _{DD} Voltage	DVDD		2.70		5.25	V
Power-Supply Rejection AV _{DD}	PSRA	(Note 7)		80		dB
Power-Supply Rejection DV _{DD}	PSRD	(Note 7)		100		dB
AVED Current (Notes 8, 9)					640	
	IAVDD	Standby mode			305	μΑ
		$DV_DD = +5.25V$			320	
DV _{DD} Current (Notes 8, 9)	IDVDD	$DV_{DD} = +3.3V$			180	μΑ
		Standby mode			20	
DAC POWER SUPPLY						
DAC Supply Voltage	VDAC_VDD		2.70		5.25	V
DAC Supply Current				0.10	0.21	mA
LINEAR REGULATOR AND V/I CO	ONVERTER F	POWER REQUIREMENTS	r			
REG_AMP Supply Voltage	VREG_AMP		4.75		5.25	V
REG_AMP Supply Current				0.19	0.30	mA
REG_VDD Voltage	VREG_VDD			5.20		V

ELECTRICAL CHARACTERISTICS (continued)

 $(AV_{DD} = DV_{DD} = DAC_VDD = +2.7V$ to +5.25V, GND = 0, LEDG = 0, $V_{LEDV} = +2.7V$ to +5.25V, $V_{REF+} - V_{REF-} = 2.048V$ (external reference), $V_{EXT} = 7V$, $V_{REG_AMP} = +5.0V$, $C_{REF+} = 0.1\mu$ F, REF- = GND, $C_{NEGV} = 0.1\mu$ F. Internal clock mode, unless otherwise noted. All specifications are at $T_A = T_{MIN}$ to T_{MAX} . Typical values are at $T_A = +25^{\circ}$ C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	МАХ	UNITS
REG_VDD Supply Current		Includes 20mA programmed current		25.2	27.4	mA
LED DRIVERS (Table 7)	•	·	•			•
LED Supply Voltage	VLEDV		2.70		5.25	V
LED Shutdown Supply Current	ISHDN				10	μΑ
LED Supply Current	ILEDV	Seven segments and decimal point on, R_{SET} = 25k Ω		176	180	mA
Diaplay Saan Pata	face	MAX1366		512		LI-7
Display Scall Hate	IOSC	MAX1368		640		пи
Segment Current Slew Rate	I _{SEG} /∆t			25		mA/µs
DIG_ Voltage Low	VDIG	I _{DIG} _ = 176mA		0.178	0.300	V
Segment-Drive Source-Current Matching	ΔI_{SEG}			3	±10	%
Segment-Drive Source Current	ISEG	V_{LEDV} - V_{SEG} = 0.6V, R_{SET} = 25k Ω	15.0	21.5	25.5	mA
LED Drivers Bias Current		From AV _{DD}		120		μΑ
Interdigit Blanking Time				4		μs
4-20OUT OUTPUT ACCURACY						
Zero-Scale Error		4mA or 0mA, at +25°C		±10	±50	μΑ
Zero-Scale Error Tempco				±40		ppmFS/°C
Gain Error		4mA or 0mA, at +25°C		±0.2	±0.5	%FS
Gain-Error Tempco				±25		ppmFS/°C
Span Linearity				±2	±4	μA
Power-Supply Rejection	PSR	$V_{EXT} = 7V \text{ to } 36V$		4		μA/V
Signal Path Noise		10pF to AGND on 4-20OUT		2.0		μArms
4–20mA Current Limit		Limited to 12.5 x V_{REF} / 1.28 k Ω		20		mA
TIMING CHARACTERISTICS (No	tes 11, 12, Fi	gure 8)				
SCLK Operating Frequency	f SCLK	$DV_{DD} = 2.7V$	0		4.2	MHz
SCLK Pulse-Width High	tсн		100			ns
SCLK Pulse-Width Low	tCL		100			ns
DIN-to-SCLK Setup	tDS		50			ns
DIN-to-SCLK Hold	tDH		0			ns
CS Fall to SCLK Rise Setup	tcss		50			ns
SCLK Rise to \overline{CS} Rise Hold	tCSH		0			ns
SCLK Fall to DOUT Valid	tDO	C _{LOAD} = 50pF, Figures 11, 12			120	ns

ELECTRICAL CHARACTERISTICS (continued)

 $(AV_{DD} = DV_{DD} = DAC_VDD = +2.7V$ to +5.25V, GND = 0, LEDG = 0, $V_{LEDV} = +2.7V$ to +5.25V, $V_{REF+} - V_{REF-} = 2.048V$ (external reference), $V_{EXT} = 7V$, $V_{REG_AMP} = +5.0V$, $C_{REF+} = 0.1\mu$ F, REF- = GND, $C_{NEGV} = 0.1\mu$ F. Internal clock mode, unless otherwise noted. All specifications are at $T_A = T_{MIN}$ to T_{MAX} . Typical values are at $T_A = +25^{\circ}$ C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	МАХ	UNITS
CS Rise to DOUT Disable	t _{TR}	C _{LOAD} = 50pF, Figures 11, 12			120	ns
CS Fall to DOUT Enable	tDV	$C_{LOAD} = 50 pF$, Figures 11, 12			120	ns

Note 1: Integral nonlinearity is the deviation of the analog value at any code from its theoretical value after nulling the gain error and offset error.

loto 2.	Offect calibrated			CAI 2 in the	On-Chine	Registers sect	ion
NOLE 2.	Unsel Campraleu.	SEE OFFSET			UII-UIIIps	negisters sect	JUII.

Note 3: Offset nulled.

Note 4: Offset-drift error is eliminated by recalibration at the new temperature.

Note 5: The input voltage range for the analog inputs is given with respect to the voltage on the negative input of the differential pair. **Note 6:** V_{AIN+} or $V_{AIN-} = -2.2V$ to +2.2V. V_{REF+} or $V_{REF-} = -2.2V$ to +2.2V. All input structures are identical. Production tested on AIN+ and REF+ only. V_{REF+} must always be greater than V_{REF-} .

Note 7: Measured at DC by changing the power-supply voltage from 2.7V to 5.25V and measuring the effect on the conversion error with external reference. PSRR at 50Hz and 60Hz exceeds 120dB with filter notches at 50Hz and 60Hz (Figure 1).

Note 8: CLK and SCLK are disabled.

Note 9: LED drivers are disabled.

Note 10: Power-supply currents are measured with all digital inputs at either GND or DVDD and with the device in internal clock mode.

Note 11: All input signals are specified with $t_{RISE} = t_{FALL} = 5ns$ (10% to 90% of DV_{DD}) and are timed from a voltage level of 50% of DV_{DD}, unless otherwise noted.

Note 12: See the serial-interface timing diagrams (Figures 7-11).

Typical Operating Characteristics

 $(A_{VDD} = D_{VDD} = +5V, V_{DAC_VDD} = +5.0V, GND = 0, LEDG = 0, V_{LEDV} = +2.7V$ to +5.25V, $V_{REF+} - V_{REF-} = 2.048V$ (external reference), $V_{EXT} = 7V$, $C_{REF+} = 0.1\mu$ F, REF- = GND, $C_{NEGV} = 0.1\mu$ F, RANGE bit = 1, internal clock mode. $T_A = +25^{\circ}$ C, unless otherwise noted.)





Typical Operating Characteristics

(AvDD = DvDD = +5V, VDAC_vDD = +5.0V, GND = 0, LEDG = 0, VLEDV = +2.7V to +5.25V, VREF+ - VREF- = 2.048V (external reference), VEXT = 7V, CREF+ = 0.1µF, REF- = GND, CNEGV = 0.1µF, RANGE bit = 1, internal clock mode. TA = +25°C, unless otherwise noted.)



MAX1366/MAX1368

Typical Operating Characteristics

 $(A_{VDD} = D_{VDD} = +5V, V_{DAC_VDD} = +5.0V, GND = 0, LEDG = 0, V_{LEDV} = +2.7V$ to +5.25V, $V_{REF+} - V_{REF-} = 2.048V$ (external reference), $V_{EXT} = 7V$, $C_{REF+} = 0.1\mu$ F, REF- = GND, $C_{NEGV} = 0.1\mu$ F, RANGE bit = 1, internal clock mode. TA = +25°C, unless otherwise noted.)



Typical Operating Characteristics (continued)

(AVDD = DVDD = +5V, VDAC, VDD = +5.0V, GND = 0, LEDG = 0, VLEDV = +2.7V to +5.25V, VBEF+ - VBEF- = 2.048V (external reference), $V_{EXT} = 7V$, $C_{REF+} = 0.1\mu$ F, REF- = GND, $C_{NEGV} = 0.1\mu$ F, RANGE bit = 1, internal clock mode. $T_A = +25^{\circ}$ C, unless otherwise noted.)



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Pin Description

DIN	NAME	EUNCTION
1	AIN+	Positive Analog Input. Positive side of fully differential analog input. Bypass AIN+ to GND with a
2	AIN-	Negative Analog Input. Negative side of fully differential analog input. Bypass AIN- to GND with a 0.1µE or greater capacitor
3	GND	Ground. Connect to star ground.
4	AV _{DD}	Analog Positive Supply Voltage. Connect AV _{DD} to a +2.7V to +5.25V power supply. Bypass AV _{DD} to GND with a 0.1μ F capacitor.
5	DV _{DD}	Digital Positive Supply Voltage. Connect DV _{DD} to a +2.7V to +5.25V power supply. Bypass DV _{DD} to GND with a 0.1μ F capacitor.
6	SET	Segment Current Set. Connect to ground through a resistor to set the segment current. See Table 7 for segment-current selection.
7	REG_VDD	V/I Converter Regulated Supply Output. REG_ VDD is typically 2.5V.
8	REG_FORCE	REG_VDD Control. Drives the gate of external depletion mode FET.
9	REG_AMP	Regulator/Reference Buffer Supply. Connect to a 4.75V to 5.25V power supply.
10	CMP	Regulator Compensation Node. Connect a 0.1µF capacitor from CMP to REG_FORCE.
11	DAC_VDD	DAC Analog Supply. Connect DAC_VDD to a +2.7V to +5.25V power supply.
12	DACVOUT	DAC Voltage Output. DAC output impedance is typically 6.2k Ω .
13	CONV_IN	V/I Converter Input
14	4–200UT	4–20mA (0 to 16mA) Current-Loop Output. Referenced to GND.
15	GND_DAC	DAC Analog Ground. Connect to star ground.
16	GND_V/I	V/I Converter Analog Ground. Connect to star ground.
17	REF_DAC	V-to-I Converter/DAC Reference Input. Connect a voltage source for external reference operation or leave floating for internal reference. Bypass REF_DAC with a 0.1µF capacitor to GND for either internal or external reference operation.
18	EN_BPM	Active-High V/I-Converter Bipolar-Mode Enable. Set high for bipolar mode. Set low for unipolar mode.
19	EN_I	Active-High V/I-Converter 4mA Offset Enable. Set low for 0 to 16mA output. Set high for 4–20mA
20	REFSELE	DAC External Reference Selection. Set low for internal reference. Set high for external reference. Leave REF_DAC unconnected when REFSELE is low.
21	DACDATA_SEL	DAC Data-Source Select. Set high to select DAC register. Set low to have the DAC follow the ADC output.
22	CS_DAC	DAC SPI Chip Select. See Table 8.
23	CLK	External Clock Input. When the EXTCLK register bit is set to one, CLK is the master clock input for the modulator, filter, and DAC. When the EXTCLK register bit is reset to zero, the internal clock is used. The default power-on state is EXTCLK = 0 (internal clock mode). Connect CLK to GND or DV_{DD} when using internal clock.
24	EOC	Active-Low End-of-Conversion Logic Output. A logic-low at $\overline{\text{EOC}}$ indicates that a new ADC result is available in the ADC result register.



_Pin Description (continued)

PIN	NAME	FUNCTION
25	SCLK	Serial Clock Input. Apply an external clock to SCLK to facilitate communication through the serial bus. SCLK may idle high or low.
26	DOUT	Serial Data Output. DOUT presents serial data in response to register queries. Data shifts out on the falling edge of SCLK. DOUT goes high impedance when \overline{CS} is high.
27	DIN	Serial Data Input. Data present at DIN is shifted into the internal registers in response to a rising edge at SCLK when CS is low.
28	CS	Active-Low Chip-Select Input. Forcing CS low activates the serial interface. (See Table 8.)
29	LEDG	LED Segment-Drivers Ground
30	DIG0	Digit 0 Driver Out (Connected to GLED for the MAX1368)
31	DIG1	Digit 1 Driver Out
32	DIG2	Digit 2 Driver Out
33	DIG3	Digit 3 Driver Out
34	DIG4	Digit 4 Driver Out
35	SEGA	Segment A Driver
36	SEGB	Segment B Driver
37	LEDV	LED-Display Segment-Driver Supply. Connect to a +2.7V to +5.25V supply. Bypass with a 0.1 μ F capacitor to LEDG.
38	SEGC	Segment C Driver
39	SEGD	Segment D Driver
40	SEGE	Segment E Driver
41	SEGF	Segment F Driver
42	SEGG	Segment G Driver
43	SEGDP	Segment Decimal-Point Driver
44	LED_EN	Active-High LED Enable. The MAX1366/MAX1368 display driver turns off when LED_EN is low. The MAX1366/MAX1368 LED-display driver turns on when LED_EN is high.
45	NEGV	-2.5V Charge-Pump Voltage Output. Connect a 0.1µF capacitor to GND.
46	LOWBATT	Low-Battery-Voltage Monitor. When the LOWBATT input voltage is lower than 2.048V, the LOWBATT bit in the status register is set to one.
47	REF-	Negative Reference Voltage Input. For internal reference operation, connect REF- to GND. For external reference operation, bypass REF- to GND with a 0.1 μ F capacitor and set V _{REF-} from -2.2V to +2.2V (V _{REF+} > V _{REF-}).
48	REF+	Positive Reference Voltage Input. For internal reference operation, connect a 4.7 μ F capacitor from REF+ to GND. For external reference operation, bypass REF+ to GND with a 0.1 μ F capacitor and set V _{REF+} from -2.2V to +2.2V, provided that V _{REF+} > V _{REF-} .



Detailed Description

The MAX1366/MAX1368 low-power, highly integrated ADCs with LED drivers convert a $\pm 2V$ differential input voltage (one count is equal to 100µV for the MAX1366 and 1mV for the MAX1368) with a sigma-delta ADC and output the result to an LED display. An additional ± 200 mV input range (one count is equal to 10µV for the MAX1366 and 100µV for the MAX1368) is available to measure small signals with finer resolution.

In addition to displaying the results on an LED display, these devices feature a DAC and V-to-I converter for 4–20mA (or 0 to 16mA) current output that proportionally follows the ADC input. The MAX1366/MAX1368 use an external depletion-mode nMOS transistor to regulate 7V to 30V for the V/I converter. Use the 4–20mA (or 0 to 16mA) output to drive a remote display, data logger, PLC input, or other 4–20mA devices in a current loop.

The MAX1366/MAX1368 interface with a μC using an SPI-/QSPI-/MICROWIRE-compatible serial interface.

For added flexibility, the MAX1366/MAX1368 allow direct access to the ADC register, LED display register, and DAC output register using the SPI interface.

The MAX1366/MAX1368 include a 2.048V reference, internal charge pump, and a high-accuracy on-chip oscillator. The devices feature on-chip buffers for the differential input signal and external-reference inputs, allowing direct interface with high-impedance signal sources. In addition, they use continuous internal offset calibration and offer > 100dB of 50Hz and 60Hz line-noise rejection. Other features include data hold and peak detection and overrange/underrange detection.

Analog Input Protection

The MAX1366/MAX1368 provide internal protection diodes that limit the analog input range on AIN+, AIN-, REF+, and REF- from NEGV to (AV_{DD} + 0.3V). If the analog input exceeds this range, limit the input current to 10mA.



Internal Analog Input/Reference Buffers

The MAX1366/MAX1368 analog input/reference buffers allow the use of high-impedance signal sources. The input buffers' common-mode input range allows the analog inputs and the reference to range from -2.2V to +2.2V.

Modulator

The MAX1366/MAX1368 perform analog-to-digital conversions using a single-bit, 3rd-order, sigma-delta modulator. The sigma-delta modulator converts the input signal into a digital pulse train whose average duty cycle represents the digitized signal information. The modulator quantizes the input signal at a much higher sample rate than the bandwidth of the input. The MAX1366/MAX1368 modulator provides 3rd-order frequency shaping of the quantization noise resulting from the single-bit quantizer. The modulator is fully differential for maximum signal-to-noise ratio and minimum susceptibility to power-supply noise. A single-bit data stream is then presented to the digital filter to remove the frequency-shaped quantization noise.

Digital Filtering

The MAX1366/MAX1368 contain an on-chip digital lowpass filter that processes the data stream from the modulator using a SINC⁴ response:



The SINC⁴ filter has a settling time of four output data periods (4 x 200ms). The MAX1366/MAX1368 have 25% overrange capability built into the modulator and digital filter. The digital filter is optimized for the f_{CLK} equal to 4.9152MHz. The frequency response of the SINC⁴ filter is calculated as follows:



where N is the oversampling ratio, and $f_m = N \times output$ data rate = 5Hz.

Filter Characteristics

Figure 1 shows the filter frequency response. The SINC⁴ characteristic -3dB cutoff frequency is 0.228 times the first notch frequency (5Hz). The oversampling



Figure 1. Frequency Response of the SINC⁴ Filter (Notch at 60Hz)

ratio (OSR) for the MAX1368 is 128 and the OSR for the MAX1366 is 1024. The output data rate for the digital filter corresponds to the positioning of the first notch of the filter's frequency response. The notches of the SINC⁴ filter are repeated at multiples of the first notch frequency. The SINC⁴ filter provides an attenuation of better than 100dB at these notches. For example, 50Hz is equal to 10 times the first notch frequency. For large step changes at the input, allow a settling time of 800ms before valid data is read.

Clock Modes

Configure the MAX1366/MAX1368 to use either the internal oscillator or an externally applied clock to drive the modulator, filter, and DAC. Set the EXTCLK bit in the control register to zero to put the device in internal clock mode. Set the EXTCLK bit to one to put the device in external clock mode. When using the internal oscillator, connect CLK to GND or DVDD. The MAX1366/MAX1368 operate with a 4.9152MHz clock to achieve maximum rejection of 50Hz/60Hz common-mode, power-supply, and normal-mode noise.

Internal Clock Mode

The MAX1366/MAX1368 contain an internal oscillator. The power-up condition for the MAX1366/MAX1368 is internal clock operation with the EXTCLK bit in the control register equal to zero. Using the internal oscillator saves board space by removing the need for an external clock source.

External-Clock Mode

For external clock operation, set the EXTCLK bit in the control register to one and drive CLK with a 4.9152MHz



Figure 2. Segment Connection for the MAX1366 (4.5 Digits)



Figure 3. Segment Connection for the MAX1368 (3.5 Digits)

clock source for best 50Hz/60Hz rejection performance. Other external clock frequencies allow for custom conversion rates. A 2.4576MHz clock signal reduces the conversion rate and the LED update rate by a factor of two while keeping good 50Hz/60Hz noise rejection. The MAX1366/MAX1368 operate with an external clock source of up to 5.05MHz.

Charge Pump

The MAX1366/MAX1368 contain an internal charge pump to provide the negative supply voltage for the internal analog input/reference buffers. The bipolar input range of the analog input/reference buffers allows this device to accept negative inputs with high source impedances. Connect a 0.1μ F capacitor from NEGV to GND.

LED Driver (Table 1)

The MAX1366 has a 4.5-digit common-cathode display driver, and the MAX1368 has a 3.5-digit common-cathode display driver.

Figures 2 and 3 show the connection schemes for a standard seven-segment LED display. The LED update rate is 2.5Hz.

The MAX1366/MAX1368 automatically display the results of the ADC, if desired. The MAX1366/MAX1368 also allow independent control of the LED driver through the serial interface, allowing for data processing of the ADC result before showing the result on the LED. Additionally, each LED segment can be individually controlled (see the *LED Segment-Display Register* sections).

SEG_SEL	SPI/ADC	HOLD	PEAK	DISPLAY VALUES FORM
1	Х	Х	Х	LED segment registers
0	1	Х	х	LED display register (user written)
0	0	1	Х	LED display register
0	0	0	1	Peak register
0	0	0	0	ADC result register

Table 1. LED Priority Table

X = Don't care.

Figure 4 shows a typical common-cathode configuration for two digits. In common-cathode configuration, the cathodes of all LEDs in a digit are connected together. Each segment driver of the MAX1366/ MAX1368 connects to its corresponding LED's anodes. For example, segment driver SEGA connects to all LED segments designated as A. Similar configurations are used for other segment drivers.

The MAX1366/MAX1368 use a multiplexing scheme to drive one digit at a time. The scan rate is fast enough to make the digits appear to be lit. Figure 5 shows the data-timing diagram for the MAX1366/MAX1368 where t is the display scan period (typically around 1/512Hz or 1.9531ms). toN in Figure 5 denotes the amount of time each digit is on and is calculated as follows:

$$t_{ON} = \frac{t}{5} = \frac{1.95312\text{ms}}{5} = 390.60\mu\text{s}$$

Decimal-Point Control

The MAX1366/MAX1368 allow for full decimal-point control and feature leading-zero suppression.

Use the DPON, DPSET1, and DPSET2 bits in the control register to set the value of the decimal point (Tables 2 and 3). The MAX1366/MAX1368 overrange and underrange display is shown in Table 4.

Current Output

The MAX1366/MAX1368 feature a 4–20mA (0 to 16mA) current output for driving remote panel meters, data loggers, and process controllers in industrial applications. The DAC output is proportional to the input of the ADC and LED display. In the simplest configuration, connect DAC_VOUT directly to CONV_IN to have the current output (4–20mA or 0 to 16mA) follow the analog inputs.





Figure 4. 2-Digit Common-Cathode Configuration



Figure 5. LED Voltage Waveform

Table 2. Decimal-Point Control Table—MAX1366

DPON	DPSET1	DPSET2	DISPLAY OUTPUT	ZERO INPUT READING
0	0	0	18888	0
0	0	1	18888	0
0	1	0	18888	0
0	1	1	18888	0
1	0	0	1888.8	0.0
1	0	1	188.88	0.00
1	1	0	18.888	0.000
1	1	1	1.8888	0.0000

Table 3. Decimal-Point Control Table—MAX1368

DPON	DPSET1	DPSET2	DISPLAY OUTPUT	ZERO INPUT READING
1	0	0	1888	0.
1	0	1	188.8	0.0
1	1	0	18.88	0.00
1	1	1	1.888	0.000



Figure 7. Serial-Interface, 16-Bit, Write Timing Diagram

Custom signal conditioning can be inserted between DAC_VOUT and CONV_IN, or CONV_IN can be driven independently by a voltage source if desired. See Figures 20–23 for the transfer functions of the DAC and V/I converter.

Note: The MAX1366/MAX1368 expect a $6k\Omega$ (typ) source impedance from the voltage source driving CONV_IN.

Current Offset

Set EN_I high for a current span of 4–20mA. Set EN_I low for a current span of 0 to 16mA. See Table 5 for current output.

Unipolar Mode

Set EN_BPM low to engage unipolar operation. In unipolar mode, the current output at 4-20OUT (4–20mA or 0 to 16mA) maps the analog input voltage (0 to 2V or 0 to 200mV). Negative voltages at the analog input result in a 4mA or 0mA output, depending on the EN_I setting. See Table 5 for current output. See Figures 21 and 22.

Table 4. LED During Overrange andUnderrange Conditions

CONDITION	MAX1368	MAX1366
Overrange	1	1
Underrange	-1	-1

Bipolar Mode

Set EN_BPM high to engage bipolar operation. In bipolar mode, the current output at 4-20OUT (4-20mA or 0 to 16mA) maps the analog input voltage (±2V or ±200mV). In bipolar mode, a 0V analog input maps to midscale (12mA). See Table 5 for current output. Also see Figures 21 and 22.





Figure 8. Serial-Interface, 8-Bit, Write Timing Diagram



Figure 9. Serial-Interface, 16-Bit, Read Timing Diagram

Table 5. Current-Output Table

	CURRENT OUTPUT (mA)									
ANALOG INPUT	UNIPOLAR MODE (EN_I = LOW)	UNIPOLAR MODE (EN_I = HIGH)	BIPOLAR MODE (EN_I = LOW)	BIPOLAR MODE (EN_I = HIGH)						
Negative Full Scale	0	4	0	4						
0V	0	4	8	12						
Positive Full Scale	16	20	16	20						



Figure 10. Serial-Interface, 8-Bit, Read Timing Diagram



Figure 11. DAC Serial Interface



Figure 12. Load Circuits for Disable Time



Figure 13. Load Circuits for Enable Time



Figure 14. Strain-Gauge Application with the MAX1366/MAX1368



Figure 15. Thermocouple Application with the MAX1366/MAX1368

MAX1366/MAX1368



Figure 16. MAX1366 Transfer Function—±2V Range



Figure 17. MAX1366 Transfer Function—±200mV Range

5.2V Linear Regulator with Compensation

The MAX1366/MAX1368 feature a 5.2V linear regulator. The 5.2V regulator consists of an op amp and connections to an external depletion-mode FET. The 5.2V regulator regulates the loop voltage that powers the voltage-to-current converter and the rest of the transmitter circuitry. The regulator output voltage is available at REG_VDD and is given by the equation:

 $V_{REG_VDD} = 2.54 \times V_{REF+}$



Figure 18. MAX1368 Transfer Function—±200mV Range



Figure 19. MAX1368 Transfer Function-±2V Range

The FET breakdown and saturation voltages determine the usable range of loop voltages (V_{EXT}). The external FET parameters such as V_{GS} (off), I_{DSS}, and transconductance must be chosen so that the op amp output on the REG_FORCE pin can control the FET operating point while swinging in the range from VREG_AMP to REG_VDD. See the *Selecting Depletion Mode FET* section in the *Applications Information* section.

Connect a $0.1 \mu F$ capacitor between CMP and REG_FORCE to ensure stable operation of the regulator.





Figure 20. DAC Output Voltage vs. ADC Output Code



Figure 21. Output Current (4-20OUT) vs. ADC Output Code (Current Offset Enabled)

Leading-Zero Suppression

The MAX1366/MAX1368 include a leading-zero suppression circuitry to turn off unnecessary zeros. For example, when DPSET1 and DPSET2 = [0,0], 0.0 is displayed instead of 000.0 (MAX1366). This feature saves a substantial amount of power by not lighting unnecessary LEDs.



Figure 22. Output Current (4-20OUT) vs. ADC Output Code (Current Offset Disabled)



Figure 23. 4-200UT Output Current vs. V/I Converter Input Voltage

Interdigit Blanking

The MAX1366/MAX1368 also include interdigit-blanking circuitry. Without this feature, it is possible to see a faint digit next to a digit that is completely on. The interdigit-blanking circuitry prevents ghosting over into the next digit for a short period of time. The typical interdigit blanking time is 4µs.



Applications Information

Power-On Reset

At power-on, the serial interface, logic, LED drivers, digital filter, modulator, and DAC circuits reset. The registers return to their default values.

Serial Interface

The SPI/QSPI/MICROWIRE serial interface consists of a chip select (\overline{CS}), a serial clock (SCLK), a data in (DIN), a data out (DOUT), DAC chip select (\overline{CS} _ \overline{DAC}), and an EOC output. CS and CS_DAC enable access to registers in the MAX1366/MAX1368. CS allows a read and write to all registers of the MAX1366/MAX1368 excluding the DAC register and CS_DAC enables a write to the DAC register (see Table 8). EOC provides an endof-conversion signal with a period of 200ms (fCLK = 4.9152MHz). The MAX1366/MAX1368 update the ADC register when $\overline{\text{EOC}}$ goes high. Data is valid in the ADC register when EOC returns low. The serial interface provides access to 13 on-chip registers, allowing control to all the power modes and functional blocks. Table 6 lists the address and read/write accessibility of all the registers excluding the DAC register.

A logic-high on \overline{CS} and \overline{CS} _DAC tri-states DOUT and causes the MAX1366/MAX1368 to ignore any signals on SCLK and DIN. To clock data in or out of the internal shift register, drive \overline{CS} or \overline{CS} _DAC low. SCLK synchronizes the data transfer. The rising edge of SCLK clocks DIN into the shift register, and the falling edge of SCLK clocks DOUT out of the shift register. DIN and DOUT are transferred MSB first (data is left justified). Figures 6–10 show the detailed serial-interface timing diagrams for the 8- and 16-bit read/write operations.

All communication with the MAX1366/MAX1368, with exception of the DAC register, begins with a command byte on DIN, where the first logic one on DIN is recognized as the START bit (MSB) for the command byte. The following seven clock cycles load the command into a shift register. These 7 bits specify which of the

registers are accessed next, and whether a read or write operation takes place. Transitions on the serial clock after the command byte transfer, cause a write or read from the device until the correct number of bits have been transferred (8 or 16). Once this has occurred, the MAX1366/MAX1368 wait for the next command byte. \overline{CS} must not go high between data transfers. If \overline{CS} is toggled before the end of a write or read operation, the device mode may be unknown. Clock in 32 zeros to clear the device state and reset the interface so it is ready to receive a new command byte.

To write to the DAC register, pull \overline{CS}_{DAC} low and clock in 16 data bits. Data bits are clocked in MSB first (see the *DAC Operation* section).

On-Chip Registers (Excluding DAC Register)

The MAX1366/MAX1368 contain 12 on-chip registers. These registers configure the various functions of the device and allow independent reading of the ADC results and writing to the LED display. Table 6 lists the address and size of each register. The first of these registers is the status register. The 8-bit status register contains the status flags for the ADC. The second register is the 16-bit control register. This register sets the LED display controls, range modes, power-down modes, offset calibration, and the reset register function (CLR). The third register is the 16-bit overrange register, which sets the overrange limit of the analog input. The fourth register is the 16-bit underrange register, which sets the underrange limit of the analog input. Registers 5 through 7 contain the display data for the individual segments of the LED. The eighth register contains the custom offset value. The ninth register contains the 16 MSBs of the ADC conversion result. The 10th register contains the LED data. The 11th register contains the peak analog input value. The last register contains the lower 4 LSBs of the 20-bit ADC conversion result.

REGISTER	ADDRESS RS[4:0]	NAME	WIDTH	ACCESS
1	00000	Status register	8	Read only
2	00001	Control register	16	R/W
3	00010	Overrange register	16	R/W
4	00011	Underrange register	16	R/W
5	00100	LED segment-display register 1	16	R/W
6	00101	LED segment-display register 2	16	R/W
7	00110	LED segment-display register 3	8	R/W
8	00111	ADC custom offset register	16	R/W
9	01000	ADC result register (16 MSBs)	16	R/W
10	01001	LED data register	16	R/W
11	01010	Peak register	16	R/W
12	10100	ADC result register 2 (4 LSBs)	8	R/W
	All other addresses	Reserved		_

Table 6. Register-Address Table

Table 7. Segment-Current Selection

R _{ISET} (kΩ)	I _{SEG} (mA)
25	20
50	10
100	5
500	1
> 2500	LED driver disabled

Table 8. $\overline{\text{CS}}$ and $\overline{\text{CS}}_{\text{DAC}}$ Table

DESCRIPTION	CS	CS_DAC
Reserved.	0	0
Read or write to on-chip registers excluding the DAC register.	0	1
Write to the DAC register only.	1	0
DOUT is high impedance. DIN and SCLK are ignored.	1	1

Table 9. FET Characteristics

FET TYPE	n-CHANNEL DEPLETION MODE
I _{DS}	30mA
BV _{DS}	(V _{EXT} * - REG_VDD) min
VPINCHOFF	REG_VDD max
Power dissipation	30mA x (V _{EXT} - REG_VDD) min

*V_{EXT} is the 7V to 30V loop voltage.

Control and Status Registers

Command Byte (Write Only)

Status Register (Read Only)

MSB							LSB
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
START(1)	R/W	RS4	RS3	RS2	RS1	RS0	Х

START: Start bit. The first 1 clocked into the MAX1366/ MAX1368 is the first bit of the command byte.

(R/W): Read/Write. Set this bit to 1 to read from the specified register. Set this bit to zero to write to the selected register. Note that certain registers are read

only. Write commands to a read-only register are ignored.

(RS4–RS0): Register address bits. RS4 to RS0 specify which register is accessed.

X: Don't care.

MSB							LSB
SIGN	OVER	UNDER	LOW_BATT	DRDY	0	0	0

Default values: 00h

This register contains the status of the conversion results.

SIGN: Latched negative-polarity indicator. Latches high when the result is negative. Clears by reading the status register, unless the condition remains true.

OVER: Overrange bit. Latches high if an overrange condition occurs (the ADC result is larger than the value in the overrange register). Clears by reading the status register, unless the condition remains true.

UNDER: Underrange bit. Latches high if an underrange condition occurs (the ADC result is less than the

value in the underrange register). Clears by reading the status register, unless the condition remains true.

LOW_BATT: Low-battery bit. Latches high if the voltage at the LOWBATT is lower than 2.048V (typ). Clears by reading the status register, unless the condition remains true.

DRDY: Data-ready bit. Latches high to indicate a completed conversion result with valid data. Read the ADC result register to clear this bit.

Control Register (Read/Write)

MSB							
Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
SPI/ADC	EXTCLK	INTREF	DPON DPSET		DPSET1	PD_DIG	PD_ANA
							LSB
Bit 7	Bit 6	iit 6 Bit 5 E		Bit 3	Bit 2	Bit 1	Bit 0
HOLD	PEAK	RANGE	e CLR SEG_SEI		OFFSET_CAL1	OFFSET_ CAL2	ENABLE

Default values: 0000h

This register is the primary control register for the MAX1366/MAX1368. It is a 16-bit read/write register. It is used to indicate the desired clock and reference source. It sets the LED display controls, range modes, power-down modes, offset calibration, and the reset register function (CLR).

ENABLE: (Default = 1.) LED driver enable bit. When set to 1, the MAX1366/MAX1368 enables the LED display drivers. A 0 in this location disables the LED display drivers.

OFFSET_CAL2: (Default = 0.) Enhanced offset-calibration start bit (RANGE = 1). To achieve the lowest possible offset in the ± 200 mV input range, perform an enhanced offset calibration by setting this bit to 1. The calibration takes about nine cycles (1800ms). After the calibration completes, set this bit to zero to resume ADC conversions.



OFFSET_CAL1: (Default = 0.) Automatic offset-calibration enable bit. When set to 1, the MAX1366/ MAX1368 disable automatic offset calibration. When this bit is set to zero, automatic offset calibration is enabled.

SEG_SEL: (Default = 0.) SEG_SEL segment selection bit. When set to 1, the LED segment drivers use the LED segment registers to display individual segments that can form letters or numbers or other information on the display. The LED data register is not displayed. Send the data first to the LED segment-display registers and then set this bit high.

CLR: (Default = 0.) Clear all registers bit. When set to 1, all registers reset to their power-on reset states after \overline{CS} makes a low-to-high transition.

RANGE: (Default = 0.) Input range select bit. When set to zero, the input voltage range is $\pm 2V$. When set to 1, the input voltage range is ± 200 mV.

PEAK: (Default = 0.) Peak bit. When set to 1 (and the HOLD bit is set to zero), the LED shows the result stored in the peak register (see Table 6).

HOLD: (Default = 0.) Hold bit. When set to 1, the LED register does not update from the ADC conversion results and holds the last result on the LED. The MAX1366/MAX1368 continue to perform conversions during HOLD (Table 1).

PD_ANA: (Default = 0.) Power-down analog select bit. When set to 1, the analog circuits (analog modulator and ADC input buffers) go into the power-down mode. When set to zero, the device is in full power-up mode. **PD_DIG:** (Default = 0.) Power-down digital select bit. When set to 1, the digital circuits (digital filter and LED drivers) go into power-down mode. This also resets the values of the internal SRAM in the digital filter to zeros. When set to zero, the device returns to full power-up mode. When powering down PD_DIG, power down the LED segment drivers by clearing the ENABLE bit to zero.

DPSET[2:1]: (Default = 00.) Decimal-point selection bits (Table 2 and 3).

DPON: (Default = 0.) Decimal-point enable bit (Tables 2 and 3).

INTREF: (Default = 0.) Reference select bit. For internal reference operation, set INTREF to 1. For external reference operation, set INTREF to zero.

EXTCLK: (Default = 0.) External clock select bit. The EXTCLK bit controls selection of the internal clock or an external clock source. A 1 in this location selects the signal at the CLK input as the clock source. A zero in this location selects and powers up the internal clock oscillator.

SPI/ADC: (Default = 0.) Display select bit. The SPI/ADC bit controls selection of the data fed into LED data register. A 1 in this location selects SPI/QSPI/MICROWIRE data (user writes this data to the LED data register). A zero in this location selects the ADC result register data, unless hold or peak functions are active (Table 1).

Note: When changing any one of the following control bits: <u>OFFSET_CAL1</u>, RANGE, PD_ANA, PD_DIG, INTREF, and EXTCLK, wait 800ms before reading the ADC results.

Overrange Register (Read/Write)

MSB															LSB
D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Default values: 7CF0h (for 3.5-digit, +1999)						dash	es for tl	ne MAX	(1366 o	ra1fo	lowed I	oy three	e dash-		

4E1Fh (for 4.5-digit, +19,999)

The overrange register is a 16-bit read/write register (D15 is the MSB). When the conversion result exceeds the value in the overrange register, the OVER bit in the status register latches to 1. The LED shows a 1 followed by four

dashes for the MAX1366 or a 1 followed by three dashes for the MAX1368 (Table 4).

The data is represented in two's-complement format.